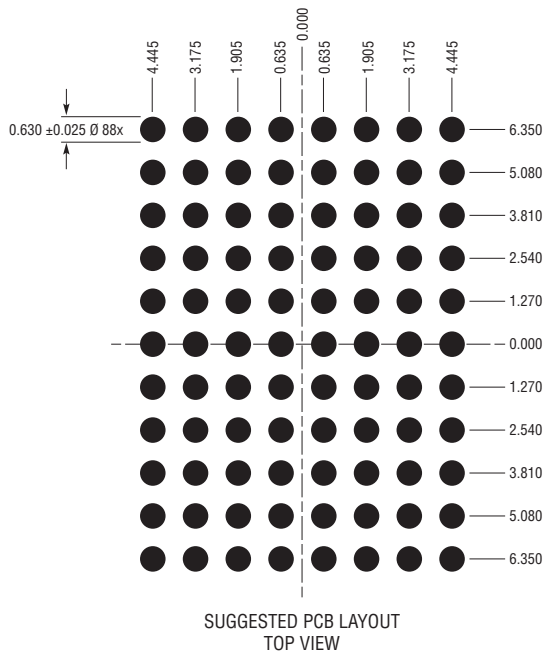
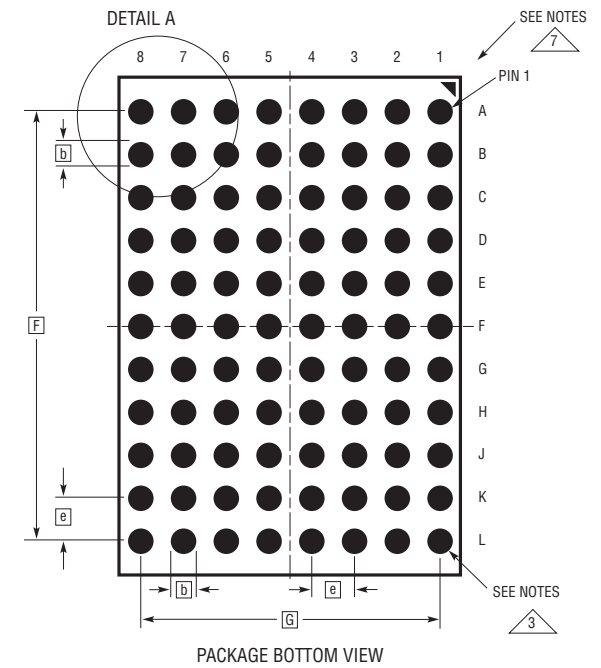
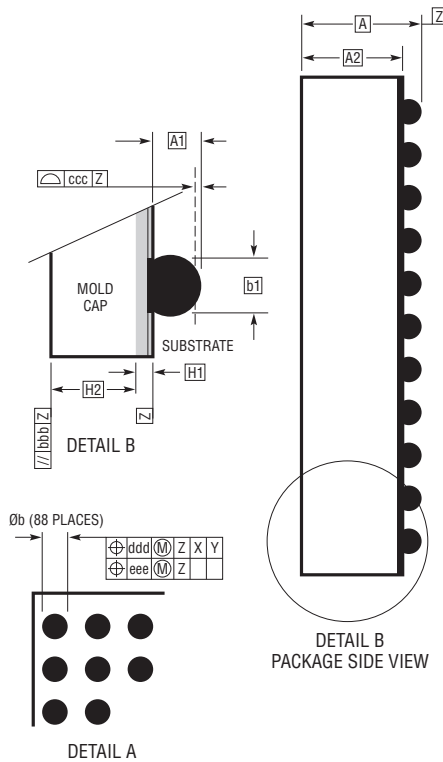
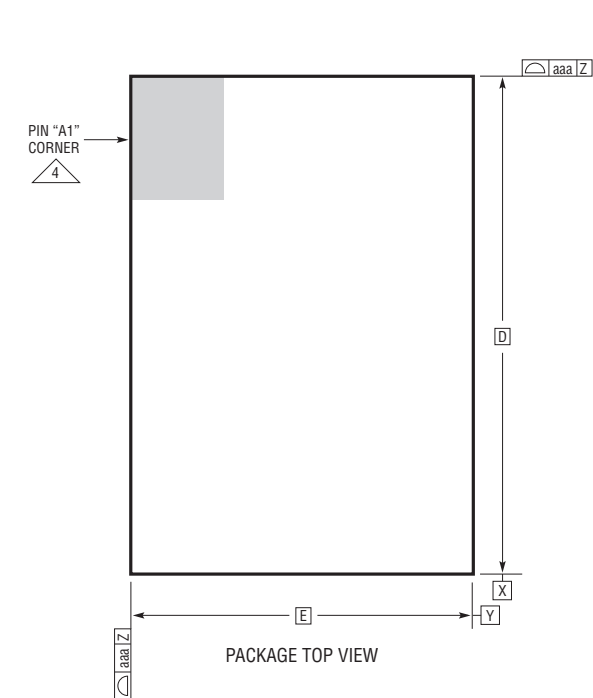


BGA Package
88-Lead (15mm × 11.25mm × 3.42mm)
 (Reference LTC DWG # 05-08-1928 Rev B)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	3.22	3.42	3.62	
A1	0.50	0.60	0.70	
A2	2.72	2.82	2.92	
b	0.60	0.75	0.90	
b1	0.60	0.63	0.66	
D	15.00			
E	11.25			
e	1.27			
F	12.70			
G	8.89			
H1	0.27	0.32	0.37	
H2	2.45	2.50	2.55	
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	

TOTAL NUMBER OF BALLS: 88

- NOTES:
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 - ALL DIMENSIONS ARE IN MILLIMETERS
 - BALL DESIGNATION PER JESD MS-028 AND JEP95
 - DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 - PRIMARY DATUM -Z- IS SEATING PLANE
 - SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu
 - PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μ Module PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

